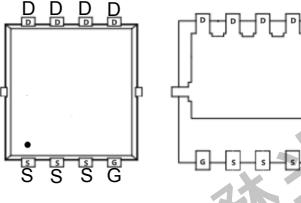
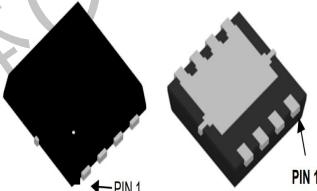
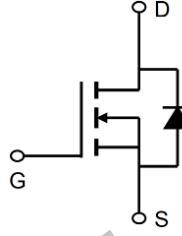


**TM30N03ADF**
**N-Channel Enhancement Mosfet**

<b>General Description</b> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <b>Applications</b> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<b>General Features</b> <p> <math>V_{DS} = 30V</math> <math>I_D = 30A</math>  <math>R_{DS(ON)} = 8 m\Omega</math> (typ.) @ <math>V_{GS}=10V</math>          100% UIS Tested          100% <math>R_g</math> Tested       </p> 			
 <b>DF:PDFN3x3-8L</b>   Marking:30N03				
<b>Absolute Maximum Ratings</b> ( $T_c=25^\circ C$ unless otherwise noted)				
Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	30	V	
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	30	A	
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	20	A	
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	111	A	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	39	mJ	
$I_{AS}$	Avalanche Current	30	A	
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	15	W	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$	
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$	
<b>Thermal Data</b>				
Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	3.6	$^\circ C/W$

**TM30N03ADF**
**N-Channel Enhancement Mosfet**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=7\text{A}$	---	8	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	---	11	18	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	1.5	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-3.84	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.04	2.1	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=7\text{A}$	---	8.4	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	3.1	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.8	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$	---	2.4	---	ns
$T_r$	Rise Time		---	72.0	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	36.0	---	
$T_f$	Fall Time		---	14.4	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	816	---	pF
$C_{\text{oss}}$	Output Capacitance		---	107.8	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	82.6	---	

**Diode Characteristics**

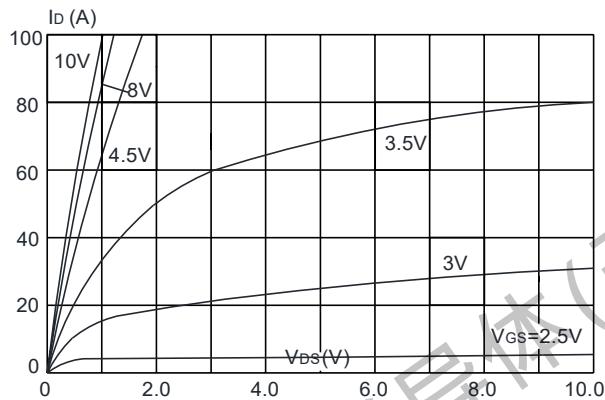
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	30	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	111	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

**Note :**

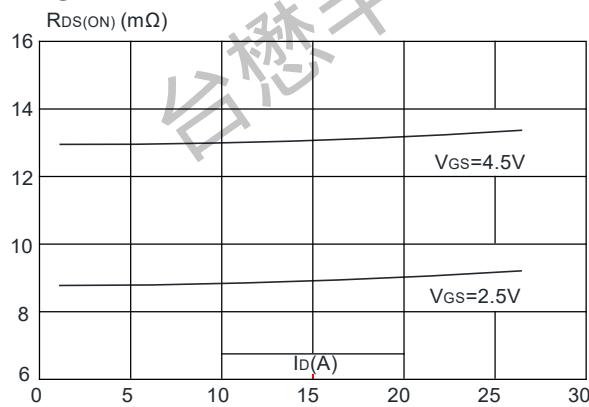
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=20\text{A}$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

## Typical Performance Characteristics

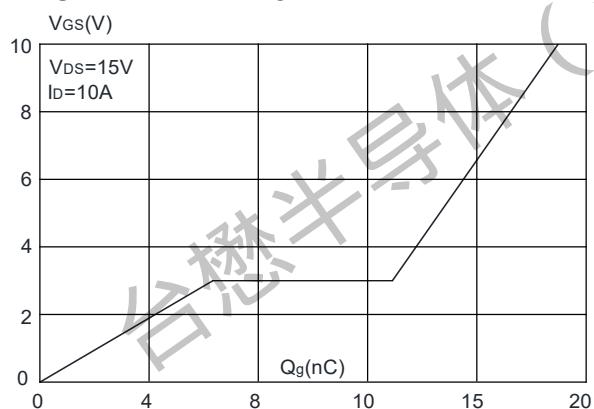
**Figure 1:** Output Characteristics



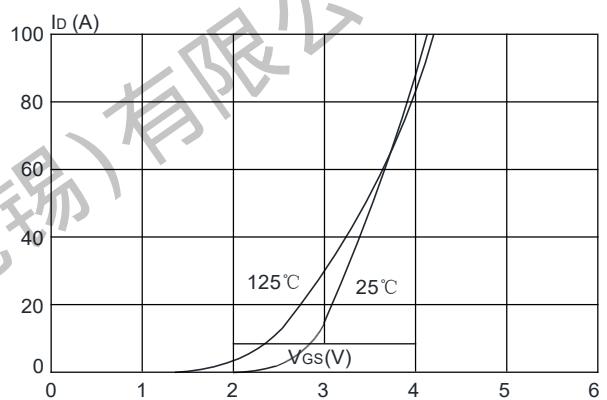
**Figure 3:** On-resistance vs. Drain Current



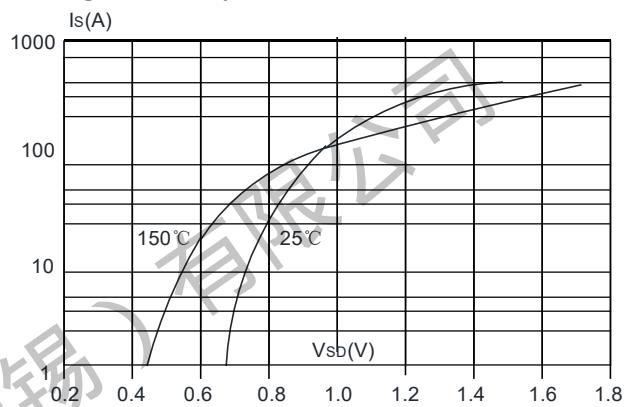
**Figure 5: Gate Charge Characteristics**



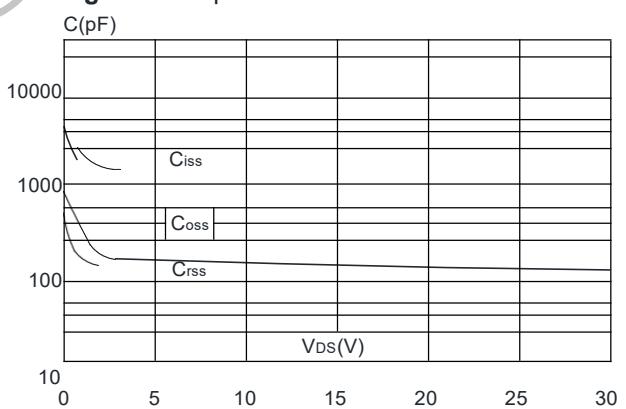
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics



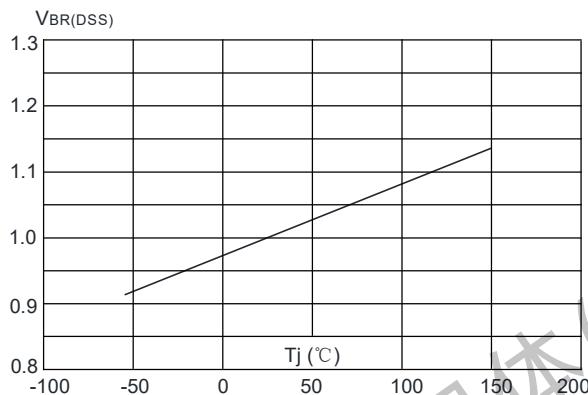
**Figure 6:** Capacitance Characteristics



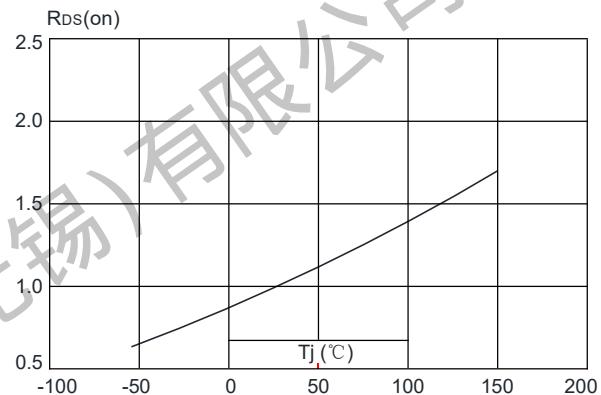
## TM30N03ADF

## N-Channel Enhancement Mosfet

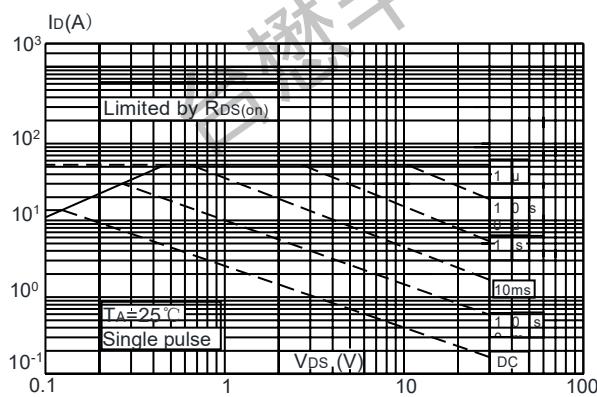
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



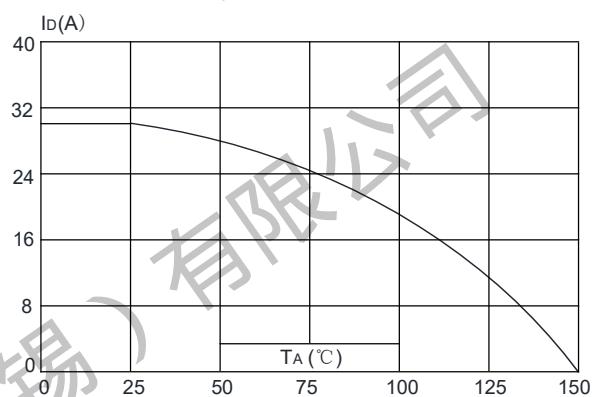
**Figure 8:** Normalized on Resistance vs. Junction Temperature



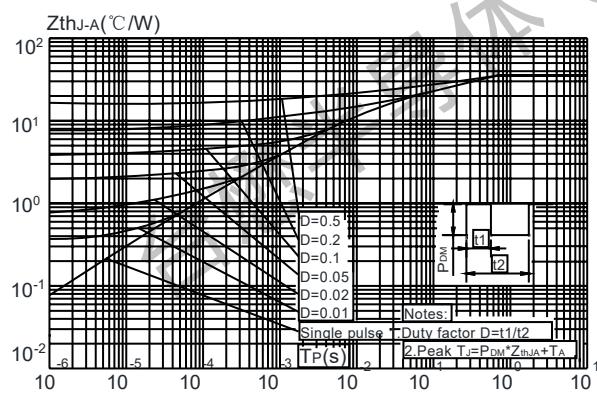
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



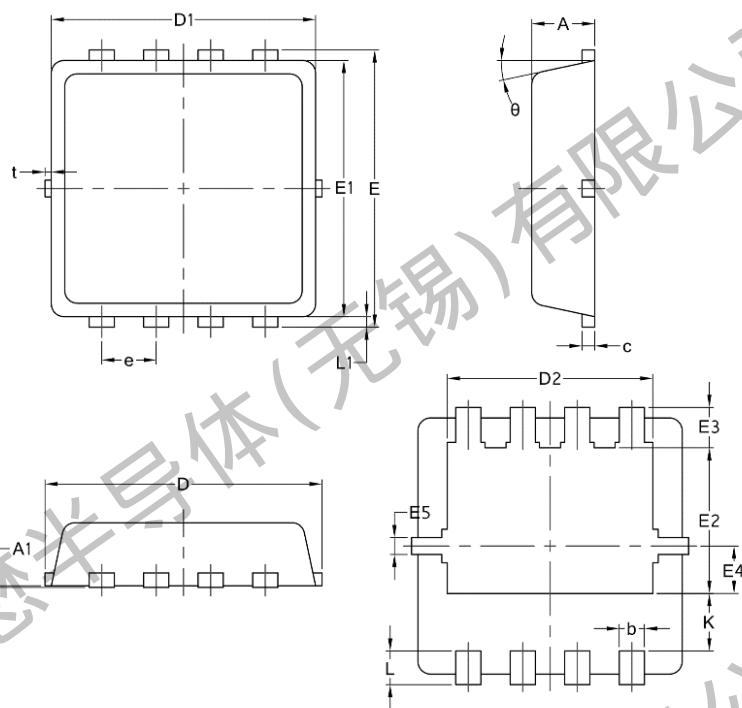
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**TM30N03ADF**

**N-Channel Enhancement Mosfet**

**Package Mechanical Data: DFN3x3-8L**

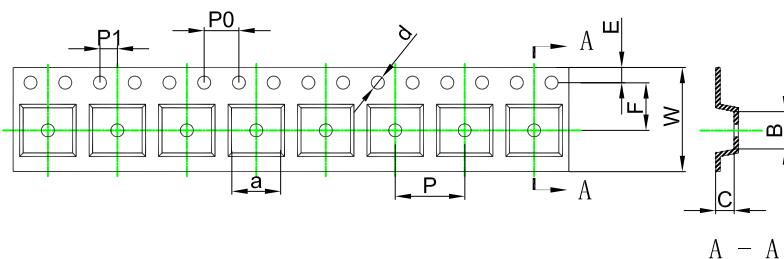


Symbol	Common mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

## TM30N03ADF

## N-Channel Enhancement Mosfet

### PDFN3x3-8L Embossed Carrier Tape

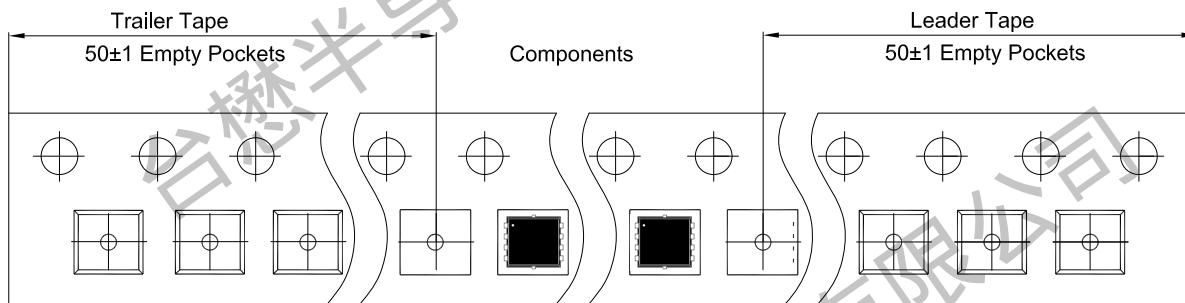


#### Packaging Description:

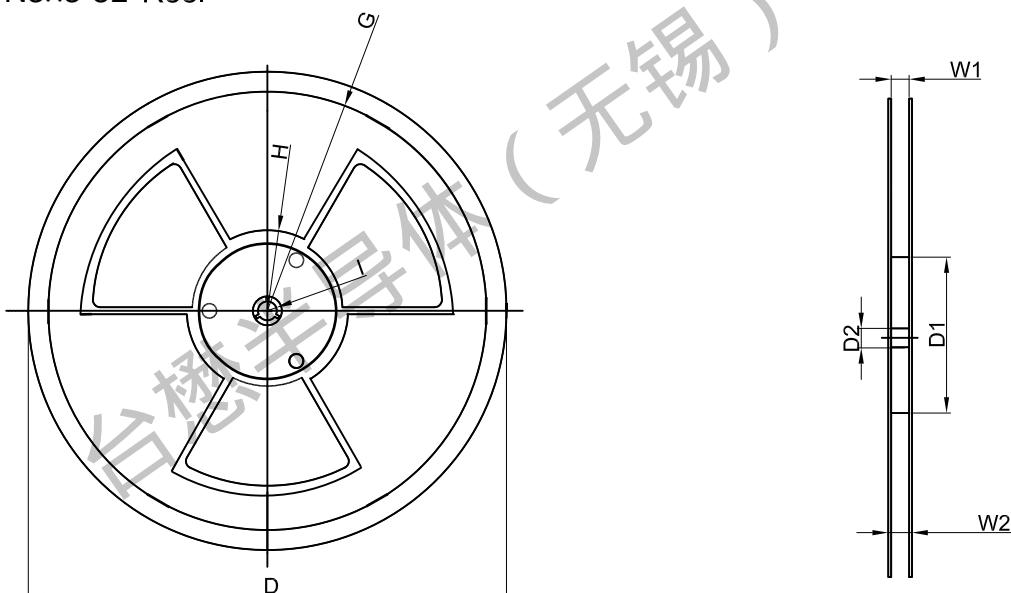
SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).  
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
PDFN3x3-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

### PDFN3x3-8L Tape Leader and Trailer



### PDFN3x3-8L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13" Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
5,000 pcs	13 inch	10,000 pcs	370×355×52	50,000 pcs	400×360×368	

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#### Revision history:

Date	Rev	Description	Page
2023.04.14	24.04	Original	